BS IEC 62047-46:2025

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Semiconductor devices — Micro-electromechanical devices

Part 46: Silicon based MEMS fabrication technology — Measurement method of tensile strength of nanoscale thickness membrane

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The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DEVICES – MICRO-ELECTROMECHANICAL DEVICES –

Part 46: Silicon based MEMS fabrication technology – Measurement method of tensile strength of nanoscale thickness membrane

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Full information on the voting for its approval can be found in the report on voting indicated in the above table.

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